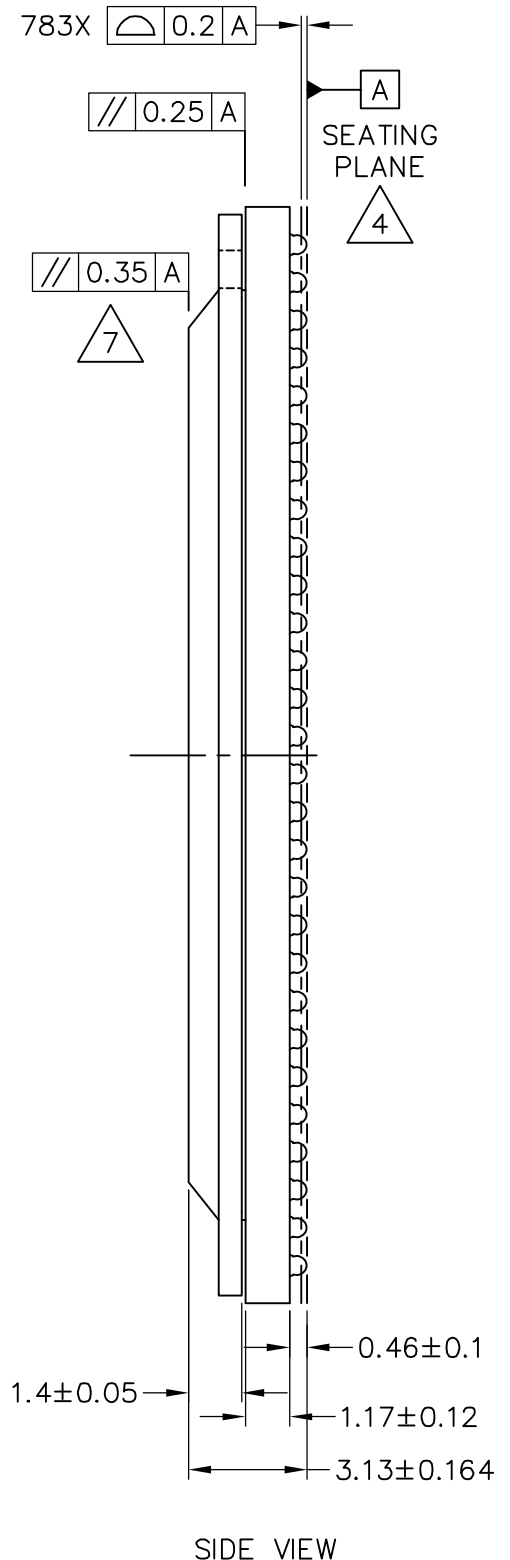
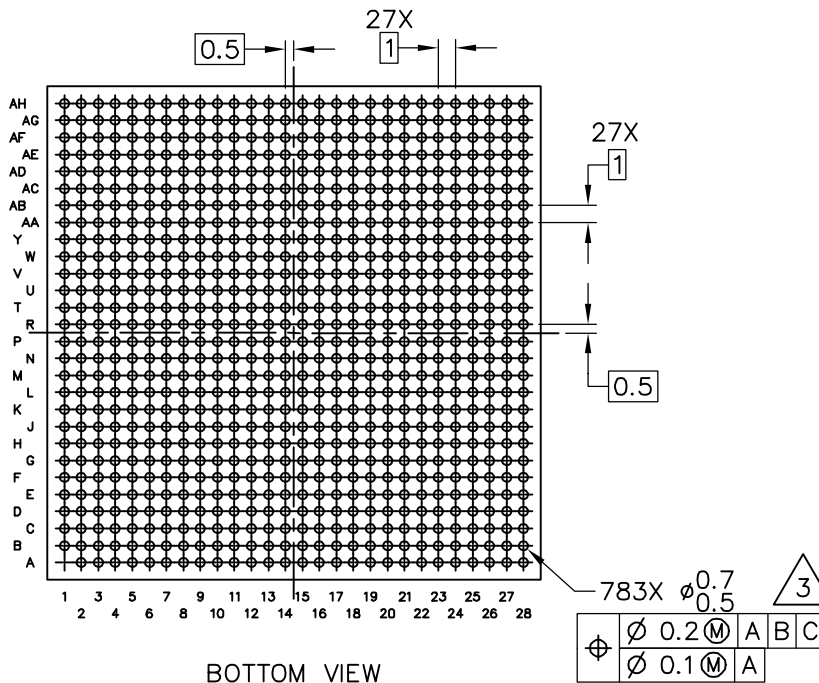
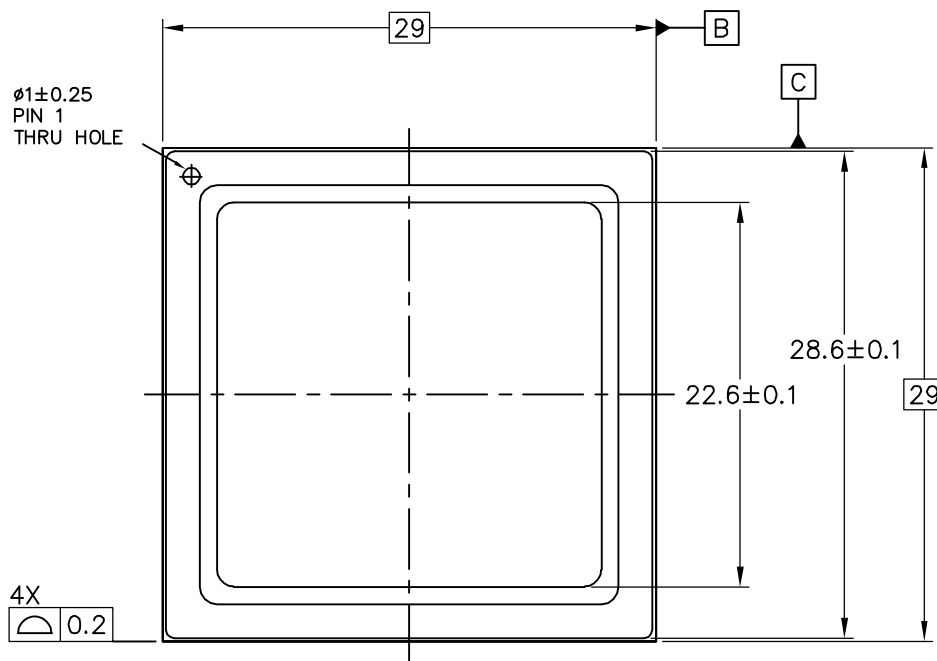




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TITLE: 783 I/O FC PBGA, 29 X 29 PKG, 1 MM PITCH, WITH STAMPED LID	DOCUMENT NO: 98ASA00295D		REV: 0
	CASE NUMBER: 2174-01		17 FEB 2011
	STANDARD: JEDEC MS-034		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

7. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

8. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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